

Bill of Materials

TI DESIGNS
TIDA-00896

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
2	!PCB1	1		TIDA-00896	Any	Printed Circuit Board	
3	C1	1	0.1uF	GRM21BR71H104KA01L	MuRata	CAP, CERM, 0.1 μ F, 50 V, +/-	0805
4	C2	1	22uF	C2012X5R1C226K125AC	TDK	CAP, CERM, 22 μ F, 16 V, +/- 10%, X5R, 0805	0805
5	C3	1	2200uF	EMVE100ATR222MKG5S	Chemi-Con	CAP, AL, 2200 μ F, 10 V, +/- 20%, SMD	KG5
6	D1	1	400V	HD04-T	Diodes Inc.	Diode, Switching-Bridge, 400 V, 0.8 A, MiniDIP	MiniDIP
7	J1, J2	2		CONREVSMA002-G	Linx Technologies	SMA Jack, 50Ohm, R/A, TH	SMA Jack
8	J3	1		61300311121	Würth Elektronik	Header, 2.54 mm, 3x1, Gold,	Header, 2.54mm, 3x1, TH
9	J4	1		1935161	Phoenix Contact	Therminal Block, 5 mm, 2-	TH, 2-Leads, Body 10x9mm, Pitch 5mm
10	TP1, TP2	2	Double	1503-2	Keystone	Terminal, Turret, TH, Double	Keystone1503-2
11	U1	1		LM2936DTX-3.3	Texas Instruments	Ultra-Low Quiescent Current LDO Voltage Regulator, 3-pin TO-252	TD03B
12	SH-J1	1		60900213421	Würth Elektronik	Shunt, 2.54mm, Gold, Black	Shunt, 2.54mm, Black

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